



- ★ Super Low Gate Charge
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

Product Summary

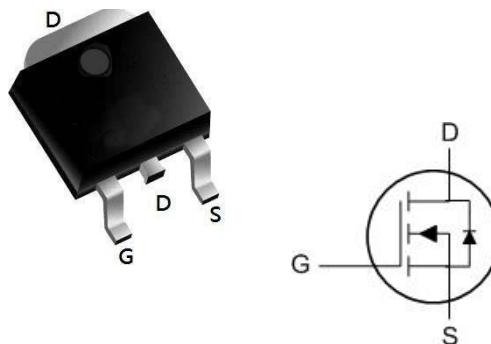
BVDSS	RDS(on)	ID
100V	13.5mΩ	60A

Description

The XXWS60N10 is the highest performance trench N-ch MOSFETs with extreme high cell density, which provide excellent RDS(on) and gate charge for most of the synchronous buck converter applications.

The XXWS60N10 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

TO252 Pin Configuration



Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	100	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current $T_c=25^\circ\text{C}$	I_D	60	A
		28.5	
Pulsed Drain Current ¹	I_{DM}	180	A
Single Pulse Avalanche Energy ²	EAS	80	mJ
Total Power Dissipation	P_D	67.5	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

Thermal Characteristics

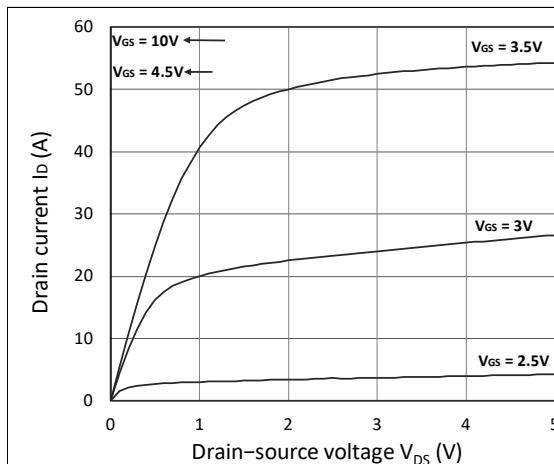
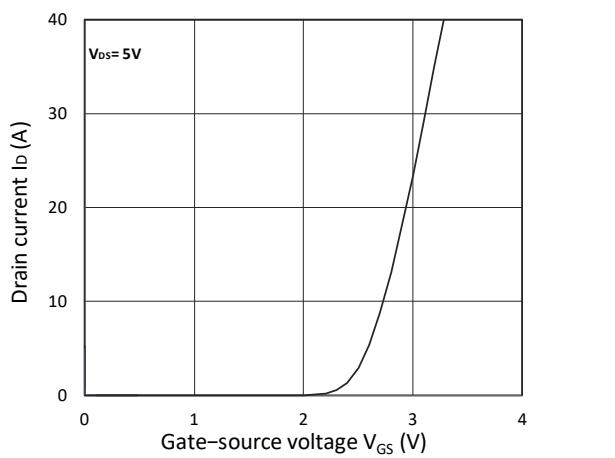
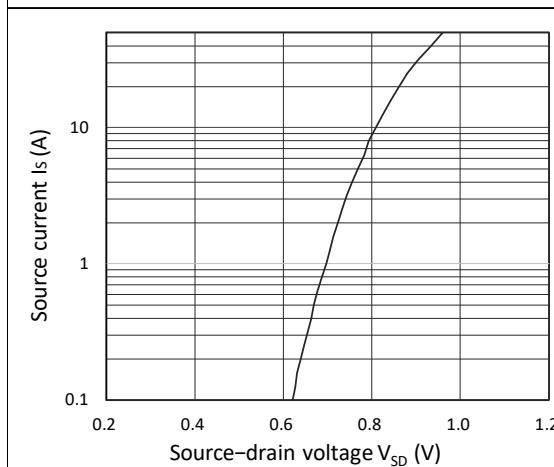
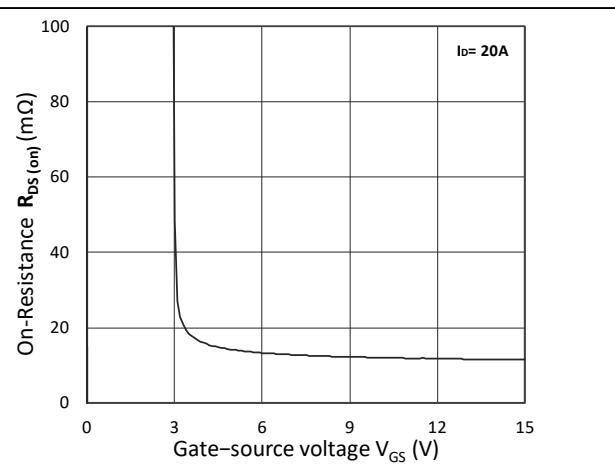
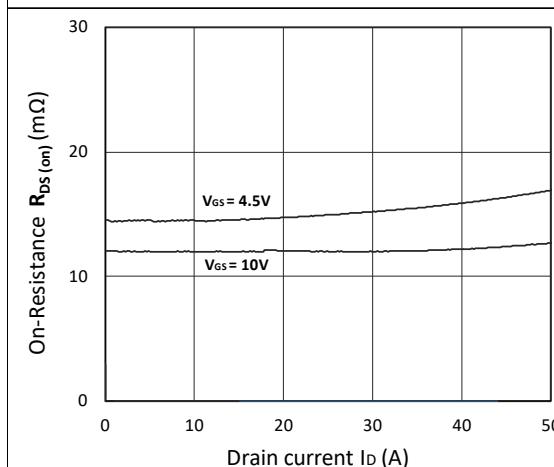
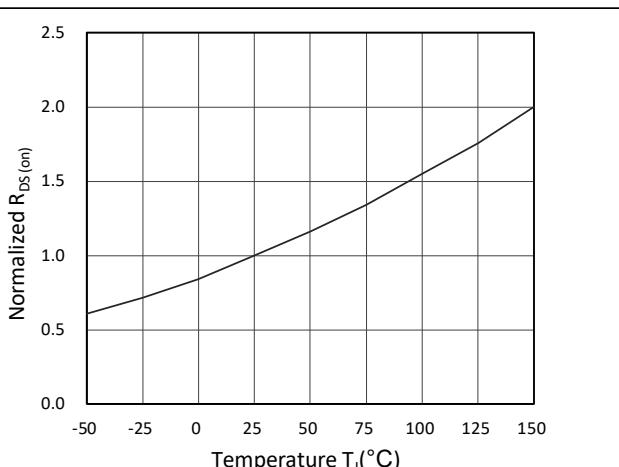
Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient ³	$R_{\theta JA}$	45	°C/W
Thermal Resistance from Junction-to-Lead	$R_{\theta JC}$	1.85	°C/W

Electrical Characteristics ($T_J = 25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	100	-	-	V
Gate-Body Leakage Current	I_{GSS}	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$	-	-	± 100	nA
Zero Gate Voltage Drain Current $T_J=25^\circ\text{C}$	I_{DSS}	$V_{\text{DS}} = 100\text{V}, V_{\text{GS}} = 0\text{V}$	-	-	1	μA
$T_J=100^\circ\text{C}$			-	-	100	
Gate-Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1	1.7	2.5	V
Drain-Source on-Resistance ⁴	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 20\text{A}$	-	13.5	17	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_D = 10\text{A}$	-	17	20	
Forward Transconductance ⁴	g_{fs}	$V_{\text{DS}} = 10\text{V}, I_D = 20\text{A}$	-	54	-	S
Dynamic Characteristics⁵						
Input Capacitance	C_{iss}	$V_{\text{DS}} = 50\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$	-	1208	-	pF
Output Capacitance	C_{oss}		-	144	-	
Reverse Transfer Capacitance	C_{rss}		-	11.3	-	
Gate Resistance	R_G	$f = 1\text{MHz}$	-	1.8	-	Ω
Switching Characteristics⁵						
Total Gate Charge	Q_g	$V_{\text{GS}} = 10\text{V}, V_{\text{DS}} = 50\text{V}, I_D = 20\text{A}$	-	22.7	-	nC
Gate-Source Charge	Q_{gs}		-	3	-	
Gate-Drain Charge	Q_{gd}		-	5	-	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, V_{\text{DD}} = 50\text{V}, R_G = 3\Omega, I_D = 20\text{A}$	-	9.2	-	ns
Rise Time	t_r		-	3.6	-	
Turn-off Delay Time	$t_{\text{d}(\text{off})}$		-	25.6	-	
Fall Time	t_f		-	4.4	-	
Body Diode Reverse Recovery Time	t_{rr}	$I_F = 20\text{A}, dI/dt = 100\text{A}/\mu\text{s}$	-	30	-	ns
Body Diode Reverse Recovery Charge	Q_{rr}		-	42	-	nC
Drain-Source Body Diode Characteristics						
Diode Forward Voltage ⁴	V_{SD}	$I_S = 20\text{A}, V_{\text{GS}} = 0\text{V}$	-	-	1.2	V
Continuous Source Current	$T_c = 25^\circ\text{C}$	I_S	-	-	60	A

Notes:

- Repetitive rating, pulse width limited by junction temperature $T_{J(\text{MAX})} = 150^\circ\text{C}$.
- The EAS data shows Max. rating. The test condition is $V_{\text{DD}} = 25\text{V}, V_{\text{GS}} = 10\text{V}, L = 0.4\text{mH}, I_{\text{AS}} = 20\text{A}$.
- The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
- The data tested by pulsed, pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
- This value is guaranteed by design hence it is not included in the production test..

Typical Characteristics

Figure 1. Output Characteristics

Figure 2. Transfer Characteristics

Figure 3. Forward Characteristics of Reverse

Figure 4. $R_{DS(on)}$ vs. V_{GS}

Figure 5. $R_{DS(on)}$ vs. I_D

Figure 6. Normalized $R_{DS(on)}$ vs. Temperature

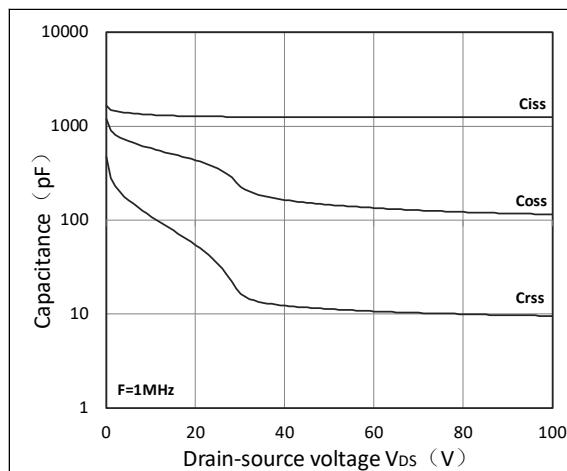
N-Ch 100V Fast Switching MOSFETs


Figure 7. Capacitance Characteristics

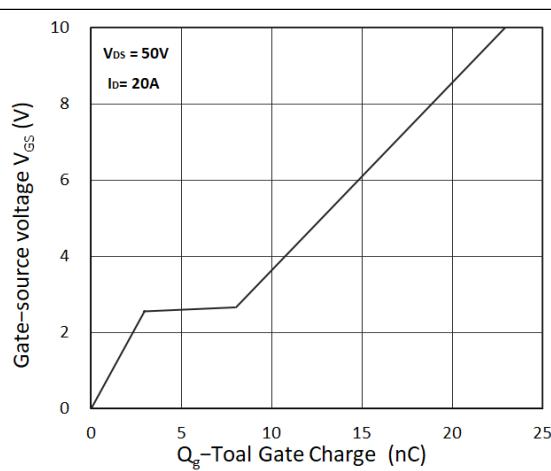


Figure 8. Gate Charge Characteristics

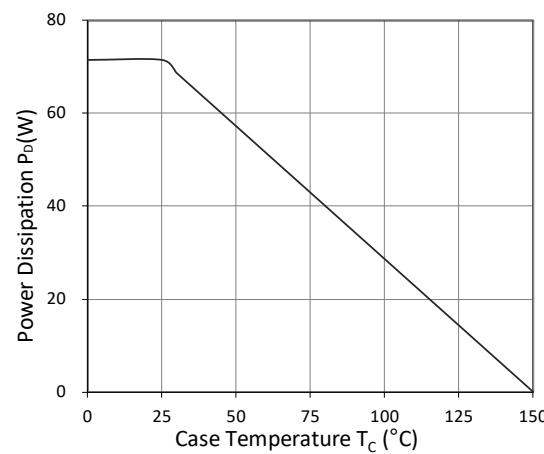


Figure 9. Power Dissipation

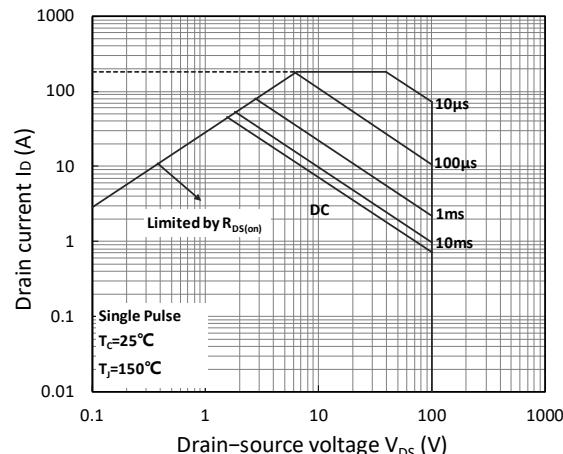


Figure 10. Safe Operating Area

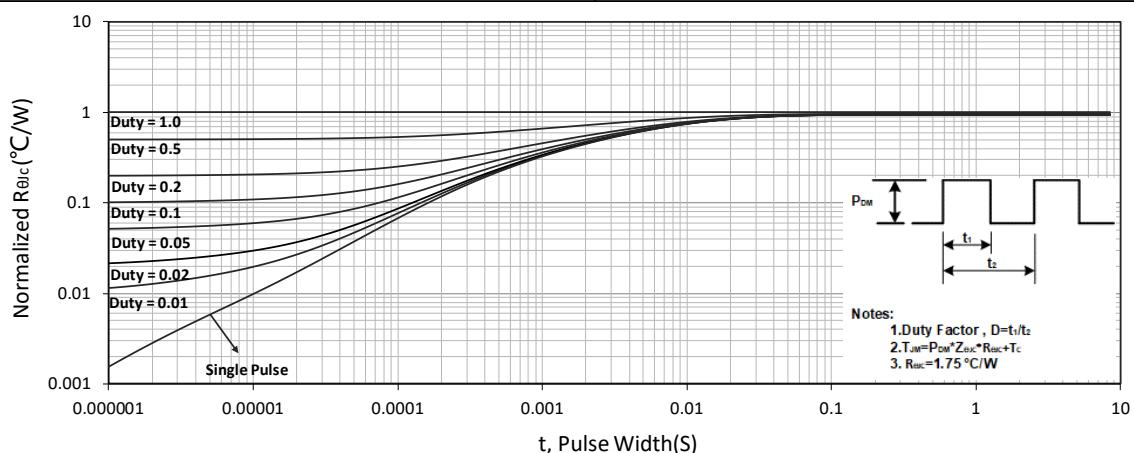
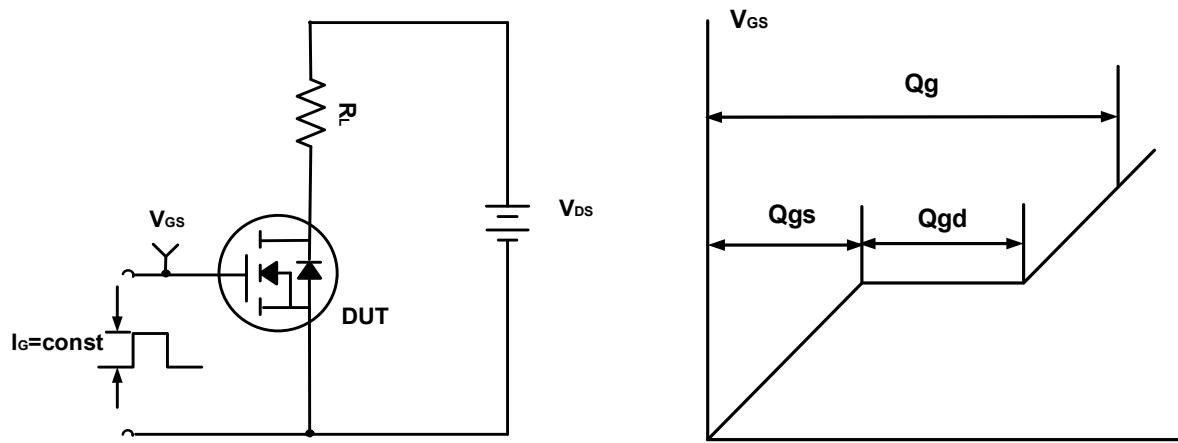
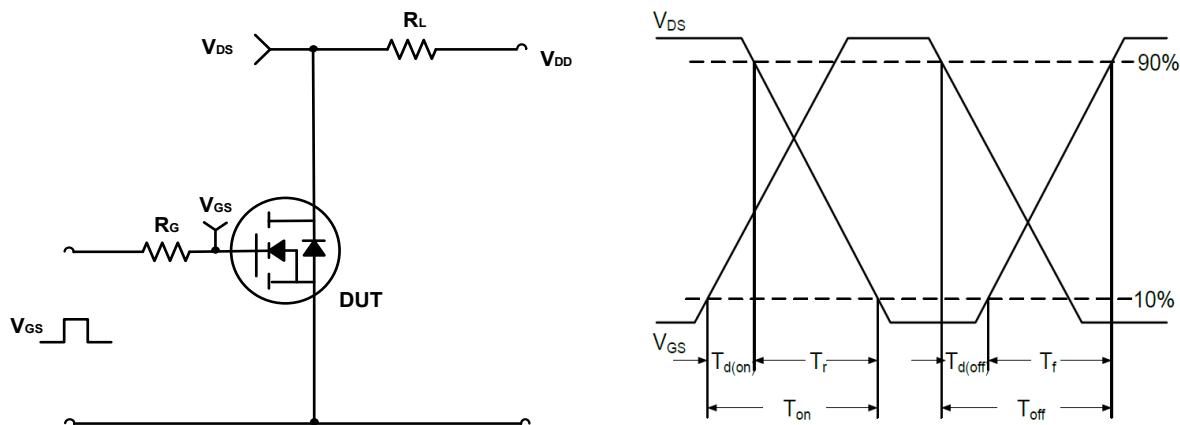
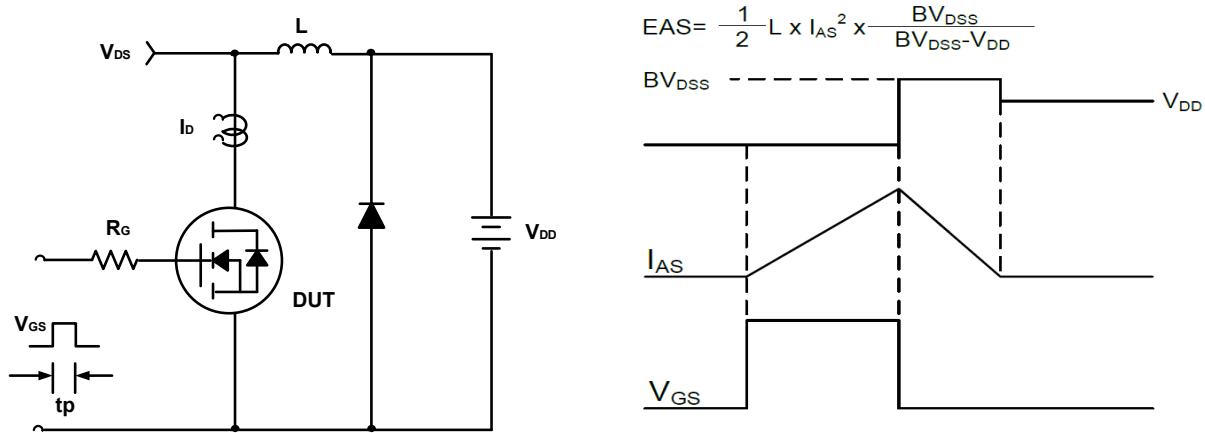
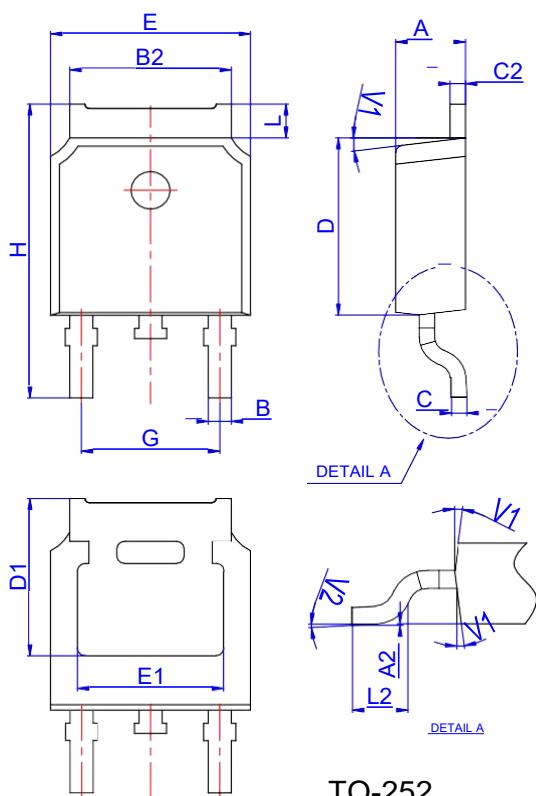


Figure 11. Normalized Maximum Transient Thermal Impedance

N-Ch 100V Fast Switching MOSFETs
Test Circuit

Figure A. Gate Charge Test Circuit & Waveforms

Figure B. Switching Test Circuit & Waveforms

Figure C. Unclamped Inductive Switching Circuit & Waveforms

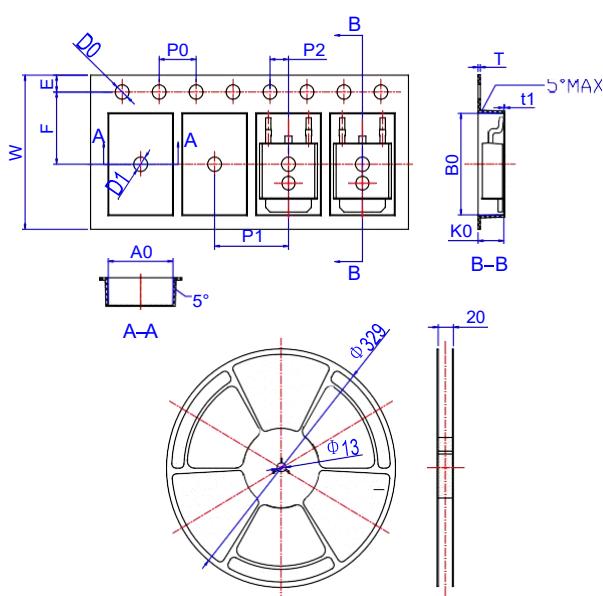
Package Mechanical Data TO 252



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

TO-252

Reel Specification-TO-252-4R



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
W	15.90	16.00	16.10	0.626	0.630	0.634
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
D0	1.40	1.50	1.60	0.055	0.059	0.063
D1	1.40	1.50	1.60	0.055	0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
A0	6.85	6.90	7.00	0.270	0.271	0.276
B0	10.45	10.50	10.60	0.411	0.413	0.417
K0	2.68	2.78	2.88	0.105	0.109	0.113
T	0.24		0.27	0.009		0.011
t1	0.10			0.004		
10P0	39.80	40.00	40.20	1.567	1.575	1.583